Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	14
Terminal Finish	100Sn
MS Number	MS010586B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.40 E-02	86.20	862000	52.76	527614
Thermosets	Epoxy resin	Proprietary	6.43 E-03	7.50	75000	4.59	45906
Thermosets	Phenol Novolac	9003-35-4	3.43 E-03	4.00	40000	2.45	24483
Other inorganic materials	Antimony Trioxide	1309-64-4	1.29 E-03	1.50	15000	0.92	9181
Thermosets	Brominated Resin	40039-93-8	4.29 E-04	0.50	5000	0.31	3060
Other inorganic materials	Carbon Black	1333-86-4	2.57 E-04	0.30	3000	0.18	1836
Subtotal			8.58 E-02	100	1000000	61.21	612081

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.81 E-02	97.50	975000	34.29	342887
Copper & its alloys	Iron	7439-89-6	1.16 E-03	2.35	23500	0.83	8264
Copper & its alloys	Zinc	7440-66-6	5.92 E-05	0.12	1200	0.04	422
Copper & its alloys	Phosphorus	7723-14-0	1.48 E-05	0.03	300	0.01	106
Subtotal			4.93 E-02	100.00	1000000	35.17	351679

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.45 E-04	100.0	1000000	0.32	3173

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.47 E-03	100.0	1000000	1.76	17636

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.62 E-04	99.99	1000000	0.26	2583

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.03 E-03	100.0	1000000	0.73	7314

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.21 E-04	80	800000	0.44	4427
Thermosets	Epoxy Resin	Proprietary	1.16 E-04	15	150000	0.08	830
Others	Curing agent & hardener	Proprietary	3.88 E-05	5	50000	0.03	277
Subtotal			7.76 E-04	100	1000000	0.55	5534

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.40 E-01**	**100.00**	**1000000**

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ANALOG DEVICES

Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	14
Terminal Finish	NiPdAu
MS Number	MS010758B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.89 E-02	87.70	877000	56.32	563214
Thermosets	Epoxy Resin	Proprietary	4.50 E-03	5.00	50000	3.21	32110
Thermosets	Phenol Resin	Proprietary	4.50 E-03	5.00	50000	3.21	32110
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.80 E-03	2.00	20000	1.28	12844
Other inorganic materials	Carbon Black	1333-86-3	2.70 E-04	0.30	3000	0.19	1927
Subtotal			9.00 E-02	100	1000000	64.22	642206

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.58 E-02	97.57	975706	32.71	327061
Copper & its alloys	Iron	7439-89-6	1.07 E-03	2.28	22789	0.76	7639
Copper & its alloys	Zinc	7440-66-6	5.93 E-05	0.13	1263	0.04	423
Copper & its alloys	Phosphorus	7723-14-0	1.14 E-05	0.02	242	0.01	81
Subtotal			4.70 E-02	100.00	1000000	33.52	335204

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.07 E-03	97.27	972697	0.76	7643
Precious metals	Palladium	7440-05-3	2.49 E-05	2.26	22621	0.02	178
Precious metals	Gold	7440-57-5	5.16 E-06	0.47	4683	0.004	37
Subtotal			1.10 E-03	100.0	1000000	0.79	7857

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.36 E-04	100.0	1000000	0.17	1684

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.25 E-03	100.0	1000000	0.89	8910

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.51 E-04	77.71	777100	0.32	3217
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.80 E-05	3.11	31100	0.01	129
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.80 E-05	3.11	31100	0.01	129
Other organic materials	Butyrolactone, gamma-	96-48-0	1.80 E-05	3.11	31100	0.01	129
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.80 E-05	3.11	31100	0.01	129
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.80 E-05	3.11	31100	0.01	129
Other organic materials	Organosilane	TS ref# 10001	1.80 E-05	3.11	31100	0.01	129
Other inorganic materials	Copper(II) oxide	1317-38-0	1.80 E-05	3.11	31100	0.01	129
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.02 E-06	0.52	5200	0.002	22
Subtotal			5.80 E-04	100	1000000	0.41	4139

			Weight (g)			Percentage (%)	PPM
Package Totals			**1.40 E-01**			**100.00**	**1000000**

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Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	14
Terminal Finish	SnPb
MS Number	MS010770B

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.40 E-02	86.2	862000	52.76	527614
Thermosets	Epoxy resin	Proprietary	6.43 E-03	7.5	75000	4.59	45906
Thermosets	Phenol Novolac	9003-35-4	3.43 E-03	4	40000	2.45	24483
Other inorganic materials	Antimony Trioxide	1309-64-4	1.29 E-03	1.5	15000	0.92	9181
Thermosets	Brominated Resin	40039-93-8	4.29 E-04	0.5	5000	0.31	3060
Other inorganic materials	Carbon Black	1333-86-4	2.57 E-04	0.3	3000	0.18	1836
Subtotal			8.58 E-02	100	1000000	61.21	612081

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.81 E-02	97.57	975706	34.31	343135
Copper & its alloys	Iron	7439-89-6	1.12 E-03	2.28	22789	0.80	8014
Copper & its alloys	Zinc	7440-66-6	6.22 E-05	0.13	1263	0.04	444
Copper & its alloys	Phosphorus	7723-14-0	1.20 E-05	0.02	242	0.01	85
Subtotal			4.93 E-02	100.00	1000000	35.17	351679

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.45 E-04	100.0	1000000	0.32	3173

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.10 E-03	85.0	850000	1.50	14990
Tin & its alloys	Lead	7439-92-1	3.71 E-04	15.0	150000	0.26	2645
Subtotal			2.47 E-03	100.0	1000000	1.76	17636

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.62 E-04	99.99	1000000	0.26	2583

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.03 E-03	100.0	1000000	0.73	7314

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.21 E-04	80	800000	0.44	4427
Thermosets	Epoxy Resin	Proprietary	1.16 E-04	15	150000	0.08	830
Others	Curing agent & hardener	Proprietary	3.88 E-05	5	50000	0.03	277
Subtotal			7.76 E-04	100	1000000	0.55	5534

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.40 E-01**	**100.00**	**1000000**

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